

# 0.8A, 200V - 600V Miniature Glass Passivated Fast Recovery Surface Mount Bridge Rectifier

#### **FEATURES**

- Ideal for automated placement
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- Small size, simple installation
- UL Recognized File # E-326243
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

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- Switching mode power supply (SMPS)
- Lighting application

#### **MECHANICAL DATA**

- Case: TO-269AA (MBS)
- Molding compound meets UL 94V-0 flammability rating
- Part No. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.12g (approximately)

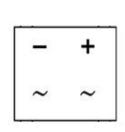
KEY PARAMETERS						
PARAMETER	VALUE	UNIT				
I <sub>F(AV)</sub>	0.8	Α				
$V_{RRM}$	200 - 600	V				
I <sub>FSM</sub>	30	Α				
$T_{JMAX}$	150	°C				
Package TO-269AA (MBS)		IBS)				
Configuration Quad						

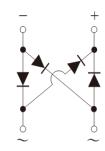






**TO-269AA (MBS)** 





ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)							
PARAMETER	SYMBOL	RMB2S	RMB4S	RMB6S	UNIT		
Marking code on the device		RMB2S	RMB4S	RMB6S			
Repetitive peak reverse voltage	$V_{RRM}$	200	400	600	V		
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	V		
Maximum DC blocking voltage	$V_{DC}$	200	400	600	V		
Maximum average forward current 60Hz sine wave resistance load on glass-expoxy P.C.B.	ı	0.5			Α		
Maximum average forward current 60Hz sine wave resistance load on aluminum substrate	I <sub>F(AV)</sub>		0.8		Α		
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I <sub>FSM</sub>	30		А			
Rating for fusing (t<8.3ms)	l <sup>2</sup> t	3.74		A <sup>2</sup> s			
Junction temperature	TJ	- 55 to +150		°C			
Storage temperature	T <sub>STG</sub>	- 55 to +150			°C		



THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-ambient thermal resistance per diode	$R_{\Theta JA}$	85	°C/W			

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)							
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT		
Forward voltage per diode (1)	$I_F = 0.4A, T_J = 25^{\circ}C$	V <sub>F</sub>	-	1	V		
	T <sub>J</sub> = 25°C		-	5	μA		
Reverse current @ rated V <sub>R</sub> per diode <sup>(2)</sup>	T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	100	μA		
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	13	-	pF		
Reverse recovery time	I <sub>F</sub> =0.5A,I <sub>R</sub> =1.0A I <sub>RR</sub> =0.25A	t <sub>rr</sub>	-	150	ns		

#### Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION							
PART NO.	PART NO. SUFFIX(*)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING		
RMBxS (Note 1, 2)	Н	RC	G	MBS	3,000 / 13" Paper reel		

#### Notes:

- 1. "x" defines voltage from 200V (RMB2S) to 600V (RMB6S)
- 2. Whole series with green compound (halogen-free)
- \*: Optional available

EXAMPLE						
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
RMB2SHRCG	RMB2S	Н	RC	G	Green compound AEC-Q101 qualified	

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#### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

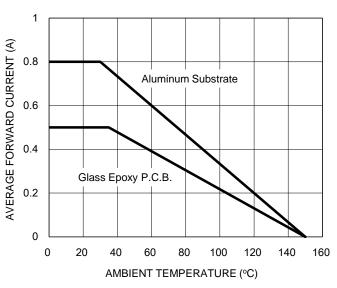


Fig.2 Typical Junction Capacitance

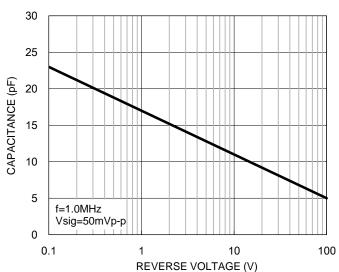


Fig.3 Typical Reverse Characteristics

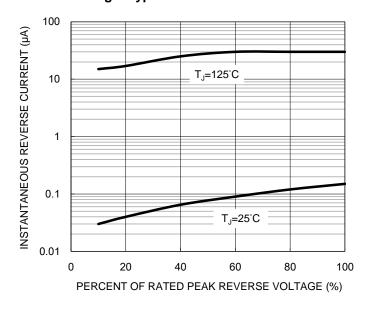
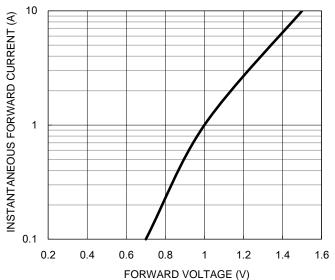


Fig.4 Typical Forward Characteristics



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## **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current

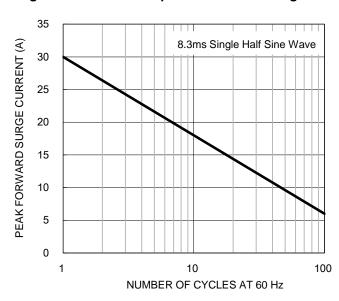
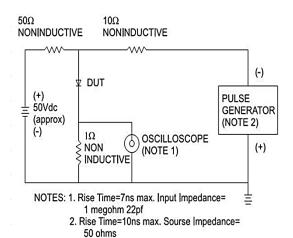
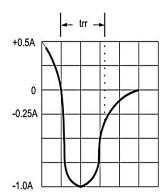


Fig.6 Reverse Recovery Time Characteristic And Test Circuit Diagram

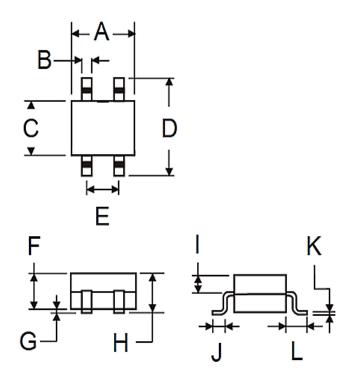






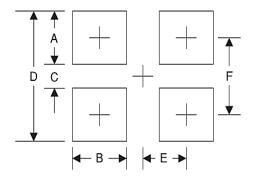
# **PACKAGE OUTLINE DIMENSIONS**

# **TO-269AA (MBS)**



r					
DIM.	Unit	(mm)	Unit (inch)		
DIIVI.	Min	Max	Min	Max	
Α	4.50	4.90	0.177	0.193	
В	0.56	0.84	0.022	0.033	
С	3.60	5.00	0.142	0.197	
D	-	6.90	-	0.272	
Е	2.20	2.60	0.087	0.102	
F	2.30	2.70	0.091	0.106	
G	-	0.20	-	0.008	
Н	-	2.90	-	0.114	
I	0.95	1.53	0.037	0.060	
J	0.70	1.10	0.028	0.043	
K	0.15	0.35	0.006	0.014	
L	1.10	2.12	0.043	0.083	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
А	1.70	0.067
В	0.90	0.035
С	4.40	0.173
D	8.10	0.319
E	1.30	0.051
F	6.30	0.248

# **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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